

Abstract of the Disclosure:

A filter device and a method for fabricating filter devices can package filters, especially acoustic wave filters, by 5 bonding a carrier (substrate) wafer carrying manufactured filters to another wafer referred to as a capping wafer. A capping wafer/substrate eliminates the need for a conventional package to protect the sensitive filters, which reduces both product size and product costs significantly. Even though 10 additional packaging is possible (i.e. in plastic molded packages, or in glob-top packages), it is not required for the reliability of the filters.

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